SEMICONDUCTOR PACKAGE AND METHOD OF ATTACHING SEMICONDUCTOR DIES TO SUBSTRATES

ABSTRACT

A method of mounting a semiconductor die on a substrate with a solder mask on a first surface includes placing a die on the solder mask, and mounting the die to the substrate by applying pressure and heat. The applied pressure ranges from a bond force of approximately 5 to 10 Kg, the heat has a temperature range from approximately 150 to 200 °C and the pressure is applied for a range of approximately 1 to 10 seconds.

Figure 1